GigaCAM Figure 1.

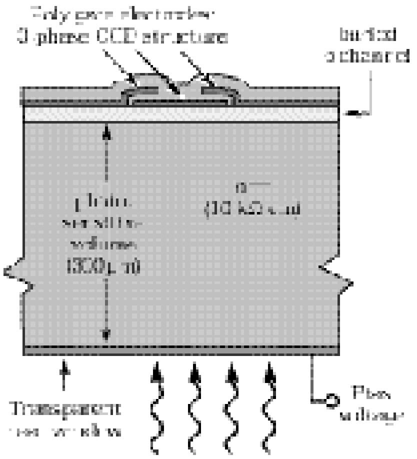

Figure 1. Cross-section of the back-illuminated, fully-depleted MOS CCD. A conventional buried channel CCD is fabricated on a high-resistivity silicon substrate. A bias voltage applied to the backside contact results in full depletion of the substrate. The CCD utilizes conventional MOS technology with the major difference being wafer thickness, 300 mm vs. the industry standard of 550 mm.